



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>
<i>* : Required Field</i>			

<b>Supplier Information</b>			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2018-03-15</b>
<b>Contact Name *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Authorized Representative *</b>	<b>Rossana Bonaccorso</b>
<b>Authorized Representative *</b>	<b>Rossana Bonaccorso</b>	<b>Representative Title</b>	<b>ADG MD Champion</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH30L06WY	BSLV*G82J2AS	A	3068	2018-03-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	4400	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.75-20.15-5.15	2	Through-hole	
Comment	DO 247			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.99	Die - Leadframe	225
Lead	9.82	Soft solder	2233

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BSLV*G82J2AS					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	11.367	mg	supplier	die	Silicon (Si)	7440-21-3		10.966	mg	964717	2493
				supplier	metallization	Aluminium (Al)	7429-90-5		0.136	mg	11963	31
				supplier	Passivation	Silicon Oxide	7631-86-9		0.045	mg	3958	10
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.005	mg	441	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.016	mg	1407	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.075	mg	6597	17
Leadframe	M-004 Copper and its alloys	2700.559	mg	supplier	polymer die coating	Probimide	Proprietary		0.124	mg	10917	28
				supplier	alloy	Copper (Cu)	7440-50-8		2696.060	mg	998334	612741
				supplier	alloy	Iron (Fe)	7439-89-6		2.700	mg	1000	614
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.810	mg	300	184
				supplier	metallization	Nickel (Ni)	7440-02-0		0.915	mg	339	208
				supplier	metallization	Phosphorus (P)	7723-14-0		0.074	mg	27	17
Soft solder	Solder	10.286	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	9.823	mg	954987	2232
				supplier	solder	Silver (Ag)	7440-22-4		0.257	mg	24985	58
				supplier	solder	Tin (Sn)	7440-31-5		0.206	mg	20028	47
Bonding wires	M-011 Other inorganic materials	3.283		supplier	wire	Aluminium (Al)	7429-90-5		3.283	mg	1000000	746
Encapsulation	M-011 Other inorganic materials	1668.308	mg	supplier	mold compound	Silica, vitreous	60676-86-0		1451.427	mg	869999	329870
				supplier	mold compound	Epoxy resin	25068-38-6		166.831	mg	100000	37916
				supplier	mold compound	Phenol resin	29690-82-2		41.708	mg	25000	9479
Connections coating	Solder	6.197	mg	supplier	mold compound	Carbon Black	1333-86-4		8.342	mg	5001	1896
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.197	mg	1000000	1408